



iS6052 AOI

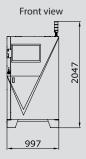
Reliable Quality Assurance for any kind of electronics production environments

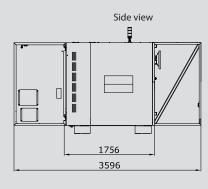


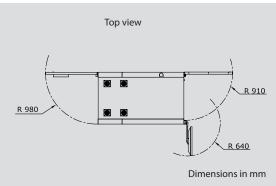




Technical Specifications iS6052 AOI







	iS6052 AOI
	Solder joints, mounting, open surfaces, character recognition, solder paste, mold, assembly
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	XM Basic
3D sensor technology	
Z-resolution	0,5 μm
Z-range	Up to 30 mm
Angled view cameras	
Number of megapixel cameras	4
Orthogonal camera	
Resolution	12 μm
Field of view	50 mm x 50 mm (2" x 2")
	Up to 60 cm ² /s
Software User interface	Viscom vVision
Statistical process control	Viscom vSPC/SPC, open interface (optional)
Verification station	Viscom vVerify
Remote diagnosis	Viscom SRC (optional)
Programming station	Viscom PST34 (optional)
Operating system	Windows®
Processor	Intel®Core™i7
PCB dimensions	508 mm x 508 mm (20" x 20")
PCB support	Optional
Transport height	900 - 950 mm ± 20 mm (35.4" - 37.4" ± 0.8")
Width adjustment Transport concept PCB clamping Upper transport clearance	Automatic
	Single-track transport system
	Pneumatic
	50 mm (2")
Lower transport clearance	50 mm (2"); 40 mm (1.6") with PCB support
Positioning unit	Synchronous linear motor
Interfaces	SMEMA, Hermes
Power requirements	230/400 V, 50 Hz, 3P/N/PE +/- 10%; 4 - 6 bar working pressure
System dimensions	997 mm x 1756 mm x 1753 mm (39.3" x 69.1" x 69") (W x D x H)
Weight	Approx. 1060 kg (2337 lbs)
	Z-resolution Z-range Angled view cameras Number of megapixel cameras Orthogonal camera Resolution Field of view User interface Statistical process control Verification station Remote diagnosis Programming station Operating system Processor PCB dimensions PCB support Transport height Width adjustment Transport concept PCB clamping Upper transport clearance Lower transport clearance Positioning unit Interfaces Power requirements System dimensions